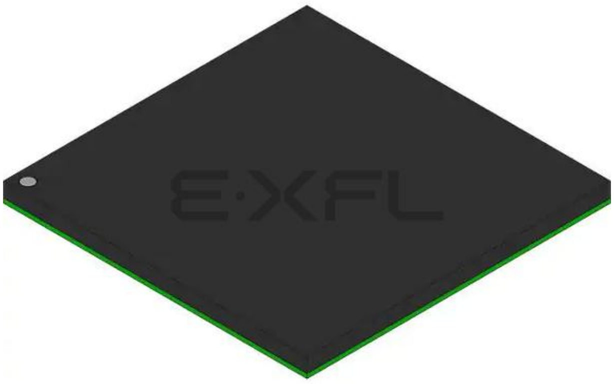

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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Active
Core Processor	MPC8xx
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	50MHz
Co-Processors/DSP	Communications; CPM
RAM Controllers	DRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10Mbps (4)
SATA	-
USB	-
Voltage - I/O	3.3V
Operating Temperature	0°C ~ 95°C (TA)
Security Features	-
Package / Case	357-BBGA
Supplier Device Package	357-PBGA (25x25)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mpc860srvr50d4

1 Overview

The MPC860 power quad integrated communications controller (PowerQUICC™) is a versatile one-chip integrated microprocessor and peripheral combination designed for a variety of controller applications. It particularly excels in communications and networking systems. The PowerQUICC unit is referred to as the MPC860 in this hardware specification.

The MPC860 implements Power Architecture™ technology and contains a superset of Freescale's MC68360 quad integrated communications controller (QUICC), referred to here as the QUICC, RISC communications proccessor module (CPM). The CPU on the MPC860 is a 32-bit core built on Power Architecture technology that incorporates memory management units (MMUs) and instruction and data caches.. The CPM from the MC68360 QUICC has been enhanced by the addition of the inter-integrated controller (I^2C) channel. The memory controller has been enhanced, enabling the MPC860 to support any type of memory, including high-performance memories and new types of DRAMs. A PCMCIA socket controller supports up to two sockets. A real-time clock has also been integrated.

Table 1 shows the functionality supported by the MPC860 family.

Table 1. MPC860 Family Functionality

Part	Cache (Kbytes)		Ethernet		ATM	SCC	Reference[1]
	Instruction Cache	Data Cache	10T	10/100			
MPC860DE	4	4	Up to 2	—	—	2	1
MPC860DT	4	4	Up to 2	1	Yes	2	1
MPC860DP	16	8	Up to 2	1	Yes	2	1
MPC860EN	4	4	Up to 4	—	—	4	1
MPC860SR	4	4	Up to 4	—	Yes	4	1
MPC860T	4	4	Up to 4	1	Yes	4	1
MPC860P	16	8	Up to 4	1	Yes	4	1
MPC855T	4	4	1	1	Yes	1	2

[1] Supporting documentation for these devices refers to the following:
1. MPC860 PowerQUICC Family User's Manual (MPC860UM, Rev. 3)
2. MPC855T User's Manual (MPC855TUM, Rev. 1)

  - Up to 8 Kbytes of dual-port RAM
  - 16 serial DMA (SDMA) channels
  - Three parallel I/O registers with open-drain capability
- Four baud-rate generators (BRGs)
  - Independent (can be tied to any SCC or SMC)
  - Allows changes during operation
  - Autobaud support option
- Four serial communications controllers (SCCs)
  - Ethernet/IEEE 802.3® standard optional on SCC1–4, supporting full 10-Mbps operation (available only on specially programmed devices)
  - HDLC/SDLC (all channels supported at 2 Mbps)
  - HDLC bus (implements an HDLC-based local area network (LAN))
  - Asynchronous HDLC to support point-to-point protocol (PPP)
  - AppleTalk
  - Universal asynchronous receiver transmitter (UART)
  - Synchronous UART
  - Serial infrared (IrDA)
  - Binary synchronous communication (BISYNC)
  - Totally transparent (bit streams)
  - Totally transparent (frame-based with optional cyclic redundancy check (CRC))
- Two SMCs (serial management channels)
  - UART
  - Transparent
  - General circuit interface (GCI) controller
  - Can be connected to the time-division multiplexed (TDM) channels
- One SPI (serial peripheral interface)
  - Supports master and slave modes
  - Supports multimaster operation on the same bus
- One I^2C (inter-integrated circuit) port
  - Supports master and slave modes
  - Multiple-master environment support
- Time-slot assigner (TSA)
  - Allows SCCs and SMCs to run in multiplexed and/or non-multiplexed operation
  - Supports T1, CEPT, PCM highway, ISDN basic rate, ISDN primary rate, user defined
  - 1- or 8-bit resolution
  - Allows independent transmit and receive routing, frame synchronization, and clocking

Table 7. Bus Operation Timings (continued)

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
B29d	WE(0:3) negated to D(0:31), DP(0:3) High-Z GPCM write access, TRLX = 1, CSNT = 1, EBDF = 0	43.45	—	35.5	—	28.00	—	20.73	—	ns
B29e	CS negated to D(0:31), DP(0:3) High-Z GPCM write access, TRLX = 1, CSNT = 1, ACS = 10, or ACS = 11, EBDF = 0	43.45	—	35.5	—	28.00	—	29.73	—	ns
B29f	WE(0:3) negated to D(0:31), DP(0:3) High-Z GPCM write access, TRLX = 0, CSNT = 1, EBDF = 1	8.86	—	6.88	—	5.00	—	3.18	—	ns
B29g	CS negated to D(0:31), DP(0:3) High-Z GPCM write access, TRLX = 0, CSNT = 1, ACS = 10, or ACS = 11, EBDF = 1	8.86	—	6.88	—	5.00	—	3.18	—	ns
B29h	WE(0:3) negated to D(0:31), DP(0:3) High-Z GPCM write access, TRLX = 1, CSNT = 1, EBDF = 1	38.67	—	31.38	—	24.50	—	17.83	—	ns
B29i	CS negated to D(0:31), DP(0:3) High-Z GPCM write access, TRLX = 1, CSNT = 1, ACS = 10, or ACS = 11, EBDF = 1	38.67	—	31.38	—	24.50	—	17.83	—	ns
B30	CS, WE(0:3) negated to A(0:31), BADDR(28:30) invalid GPCM write access [8]	5.58	—	4.25	—	3.00	—	1.79	—	ns
B30a	WE(0:3) negated to A(0:31), BADDR(28:30) invalid GPCM, write access, TRLX = 0, CSNT = 1, CS negated to A(0:31) invalid GPCM write access, TRLX = 0, CSNT = 1 ACS = 10, or ACS = 11, EBDF = 0	13.15	—	10.50	—	8.00	—	5.58	—	ns
B30b	WE(0:3) negated to A(0:31), invalid GPCM BADDR(28:30) invalid GPCM write access, TRLX = 1, CSNT = 1. CS negated to A(0:31), Invalid GPCM, write access, TRLX = 1, CSNT = 1, ACS = 10, or ACS = 11, EBDF = 0	43.45	—	35.50	—	28.00	—	20.73	—	ns
B30c	WE(0:3) negated to A(0:31), BADDR(28:30) invalid GPCM write access, TRLX = 0, CSNT = 1. CS negated to A(0:31) invalid GPCM write access, TRLX = 0, CSNT = 1, ACS = 10, ACS = 11, EBDF = 1	8.36	—	6.38	—	4.50	—	2.68	—	ns
B30d	WE(0:3) negated to A(0:31), BADDR(28:30) invalid GPCM write access, TRLX = 1, CSNT =1. CS negated to A(0:31) invalid GPCM write access TRLX = 1, CSNT = 1, ACS = 10, or ACS = 11, EBDF = 1	38.67	—	31.38	—	24.50	—	17.83	—	ns
B31	CLKOUT falling edge to CS valid—as requested by control bit CST4 in the corresponding word in UPM	1.50	6.00	1.50	6.00	1.50	6.00	1.50	6.00	ns

Figure 3 is the control timing diagram.

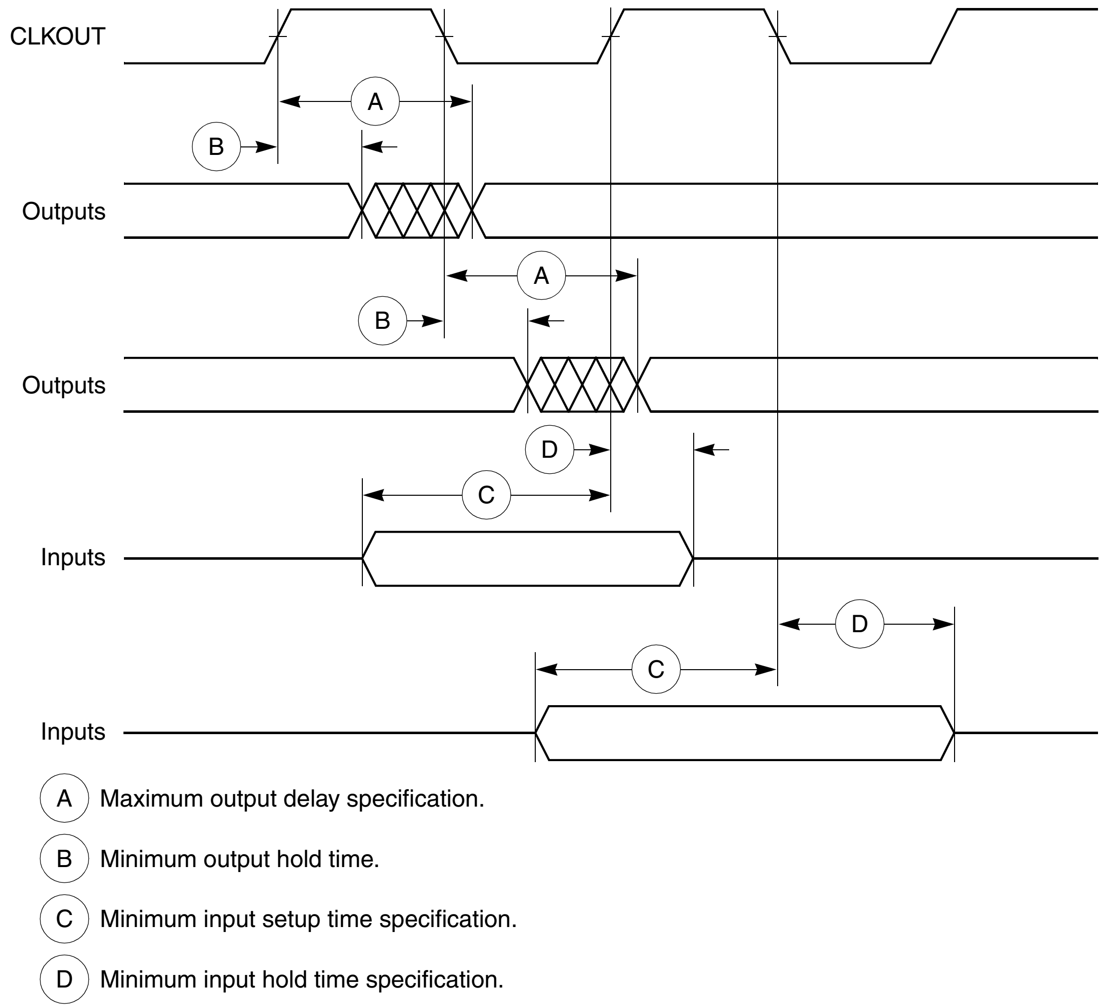


Figure 3. Control Timing

Figure 4 provides the timing for the external clock.

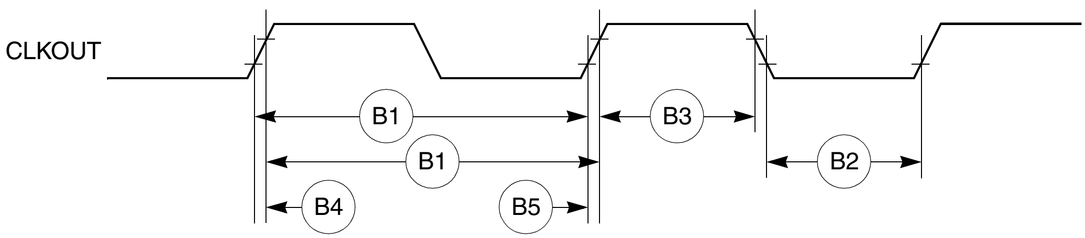


Figure 4. External Clock Timing

Figure 5 provides the timing for the synchronous output signals.

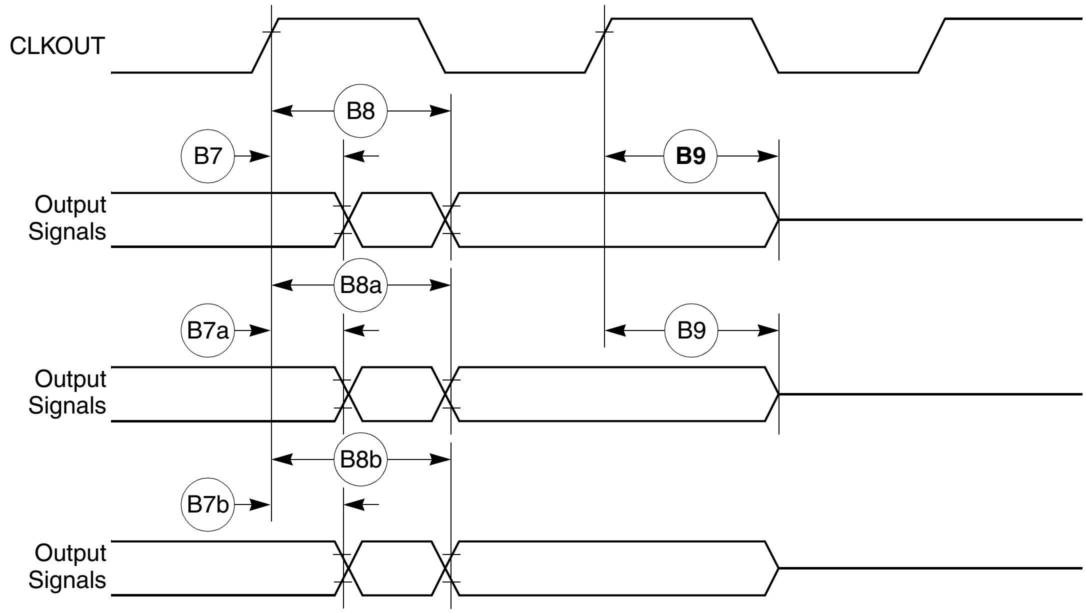


Figure 5. Synchronous Output Signals Timing

Figure 6 provides the timing for the synchronous active pull-up and open-drain output signals.

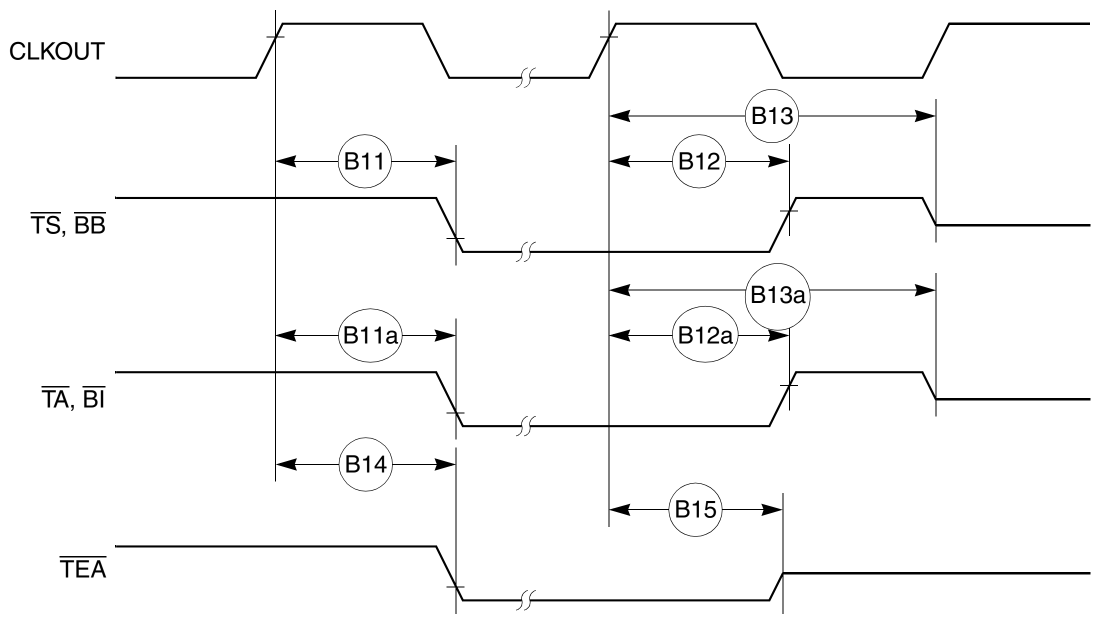


Figure 6. Synchronous Active Pull-Up Resistor and Open-Drain Outputs Signals Timing

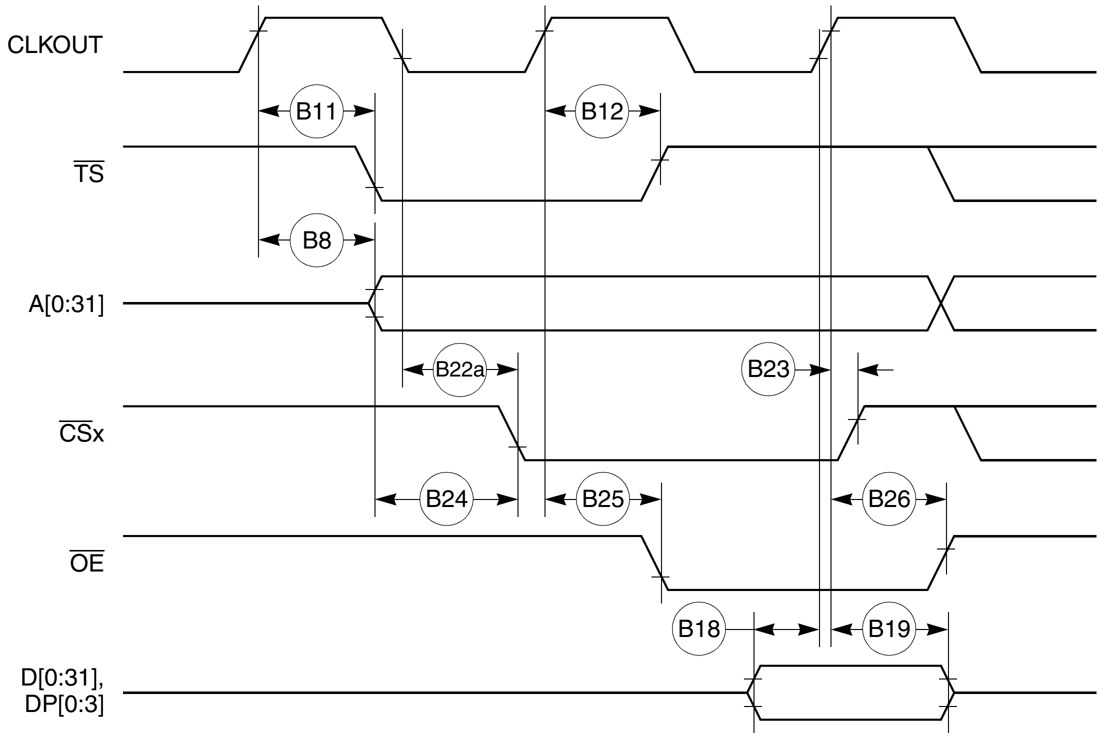


Figure 11. External Bus Read Timing (GPCM Controlled—TRLX = 0, ACS = 10)

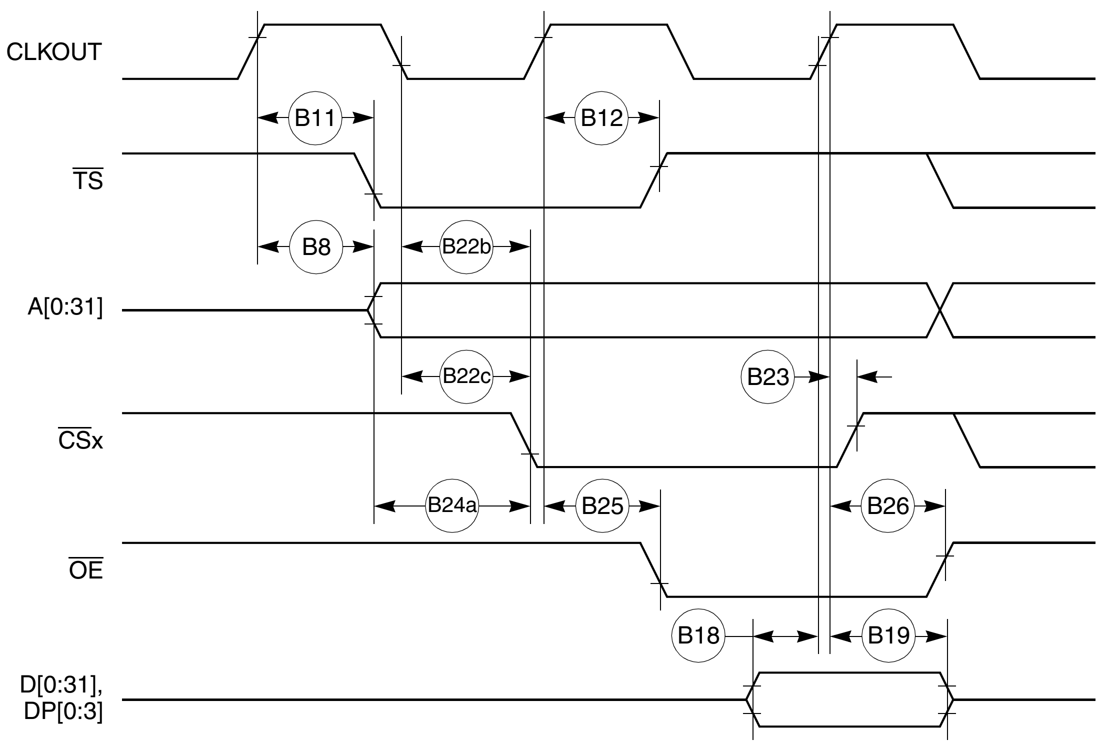


Figure 12. External Bus Read Timing (GPCM Controlled—TRLX = 0, ACS = 11)

Figure 17 provides the timing for the external bus controlled by the UPM.

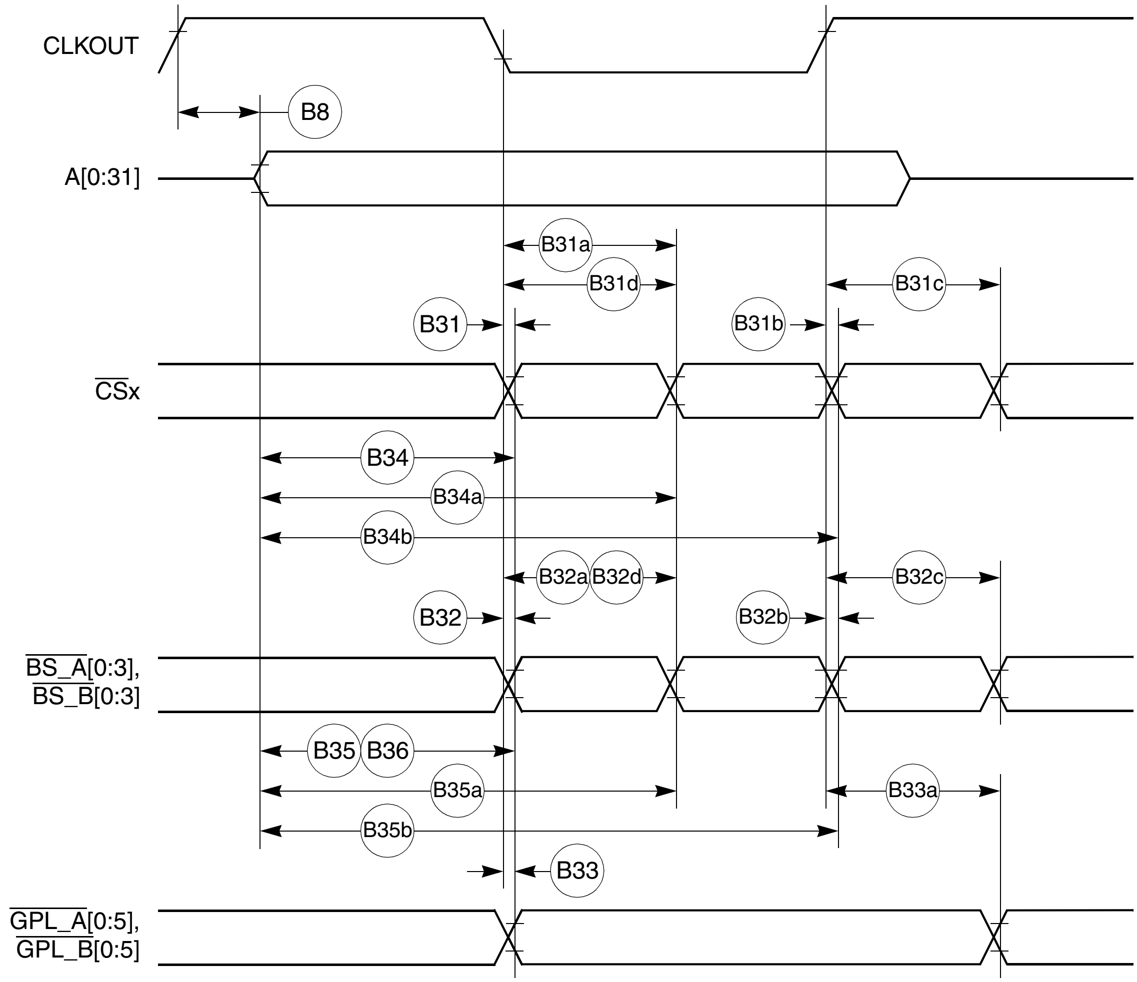


Figure 17. External Bus Timing (UPM Controlled Signals)

Table 8 provides interrupt timing for the MPC860.

Table 8. Interrupt Timing

Num	Characteristic[1]	All Frequencies		Unit
		Min	Max	
I39	$\overline{\text{IRQ}}$x valid to CLKOUT rising edge (setup time)	6.00	—	ns
I40	$\overline{\text{IRQ}}$x hold time after CLKOUT	2.00	—	ns
I41	$\overline{\text{IRQ}}$x pulse width low	3.00	—	ns
I42	$\overline{\text{IRQ}}$x pulse width high	3.00	—	ns
I43	$\overline{\text{IRQ}}$x edge-to-edge time	$4 \times T_{CLOCKOUT}$	—	—

[1] The timings I39 and I40 describe the testing conditions under which the $\overline{\text{IRQ}}$ lines are tested when being defined as level-sensitive. The $\overline{\text{IRQ}}$ lines are synchronized internally and do not have to be asserted or negated with reference to the CLKOUT.
The timings I41, I42, and I43 are specified to allow the correct function of the $\overline{\text{IRQ}}$ lines detection circuitry and have no direct relation with the total system interrupt latency that the MPC860 is able to support.

Figure 23 provides the interrupt detection timing for the external level-sensitive lines.

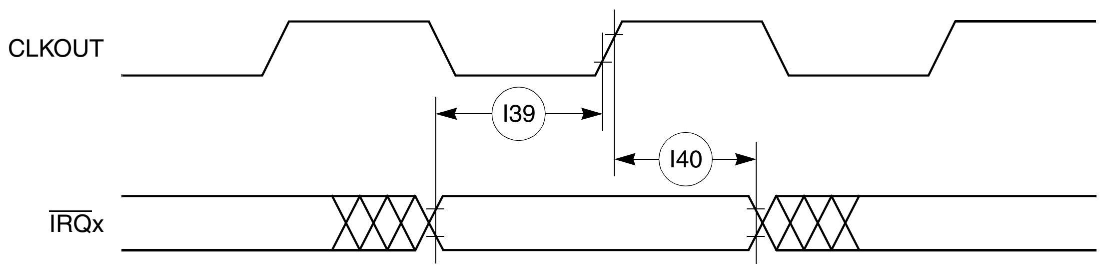


Figure 23. Interrupt Detection Timing for External Level Sensitive Lines

Figure 24 provides the interrupt detection timing for the external edge-sensitive lines.

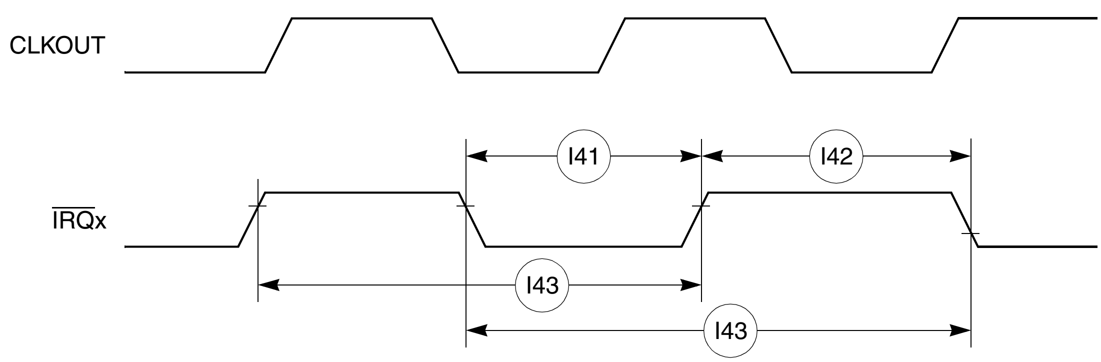


Figure 24. Interrupt Detection Timing for External Edge Sensitive Lines

Table 9 shows the PCMCIA timing for the MPC860.

Table 9. PCMCIA Timing

Num	Characteristic	33 MHz		40 MHz		50 MHz		66 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
P44	A(0:31), $\overline{\text{REG}}$ valid to PCMCIA Strobe asserted[1]	20.73	—	16.75	—	13.00	—	9.36	—	ns
P45	A(0:31), $\overline{\text{REG}}$ valid to ALE negation[1]	28.30	—	23.00	—	18.00	—	13.15	—	ns
P46	CLKOUT to $\overline{\text{REG}}$ valid	7.58	15.58	6.25	14.25	5.00	13.00	3.79	11.84	ns
P47	CLKOUT to $\overline{\text{REG}}$ invalid	8.58	—	7.25	—	6.00	—	4.84	—	ns
P48	CLKOUT to $\overline{\text{CE1}}$, $\overline{\text{CE2}}$ asserted	7.58	15.58	6.25	14.25	5.00	13.00	3.79	11.84	ns
P49	CLKOUT to $\overline{\text{CE1}}$, $\overline{\text{CE2}}$ negated	7.58	15.58	6.25	14.25	5.00	13.00	3.79	11.84	ns
P50	CLKOUT to $\overline{\text{PCOE}}$, $\overline{\text{IORD}}$, $\overline{\text{PCWE}}$, $\overline{\text{IOWR}}$ assert time	—	11.00		11.00	—	11.00	—	11.00	ns
P51	CLKOUT to $\overline{\text{PCOE}}$, $\overline{\text{IORD}}$, $\overline{\text{PCWE}}$, $\overline{\text{IOWR}}$ negate time	2.00	11.00	2.00	11.00	2.00	11.00	2.00	11.00	ns
P52	CLKOUT to ALE assert time	7.58	15.58	6.25	14.25	5.00	13.00	3.79	10.04	ns
P53	CLKOUT to ALE negate time	—	15.58		14.25	—	13.00	—	11.84	ns
P54	$\overline{\text{PCWE}}$, $\overline{\text{IOWR}}$ negated to D(0:31) invalid[1]	5.58	—	4.25	—	3.00	—	1.79	—	ns
P55	$\overline{\text{WAITA}}$ and $\overline{\text{WAITB}}$ valid to CLKOUT rising edge[1]	8.00	—	8.00	—	8.00	—	8.00	—	ns
P56	CLKOUT rising edge to $\overline{\text{WAITA}}$ and $\overline{\text{WAITB}}$ invalid[1]	2.00	—	2.00	—	2.00	—	2.00	—	ns

[1] PSST = 1. Otherwise add PSST times cycle time.
PSHT = 0. Otherwise add PSHT times cycle time.

These synchronous timings define when the $\overline{\text{WAITx}}$ signals are detected in order to freeze (or relieve) the PCMCIA current cycle. The $\overline{\text{WAITx}}$ assertion will be effective only if it is detected 2 cycles before the PSL timer expiration. See Chapter 16, “PCMCIA Interface,” in the *MPC860 PowerQUICC™ Family User’s Manual*.

Table 11 shows the debug port timing for the MPC860.

Table 11. Debug Port Timing

Num	Characteristic	All Frequencies		Unit
		Min	Max	
P61	DSCK cycle time	$3 \times T_{CLOCKOUT}$	—	—
P62	DSCK clock pulse width	$1.25 \times T_{CLOCKOUT}$	—	—
P63	DSCK rise and fall times	0.00	3.00	ns
P64	DSDI input data setup time	8.00	—	ns
P65	DSDI data hold time	5.00	—	ns
P66	DSCK low to DSDO data valid	0.00	15.00	ns
P67	DSCK low to DSDO invalid	0.00	2.00	ns

Figure 30 provides the input timing for the debug port clock.

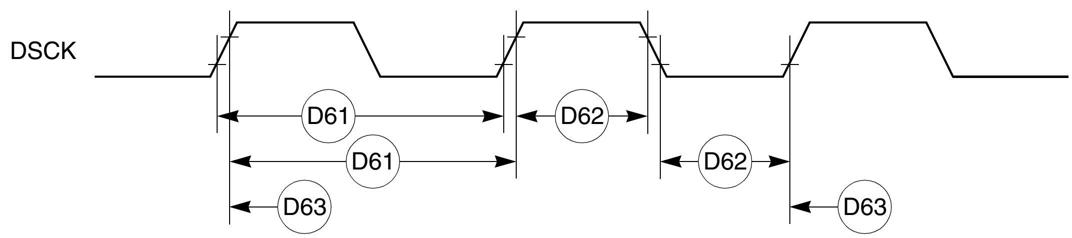


Figure 30. Debug Port Clock Input Timing

Figure 31 provides the timing for the debug port.

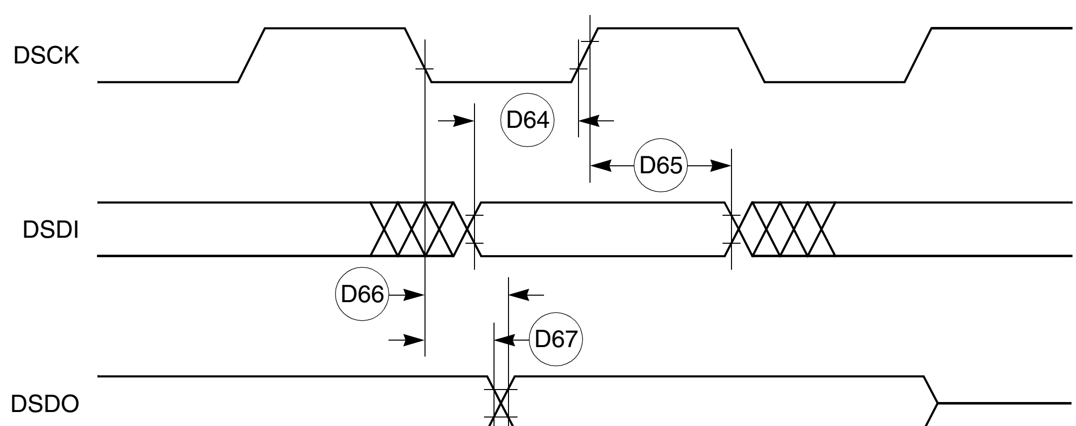


Figure 31. Debug Port Timings

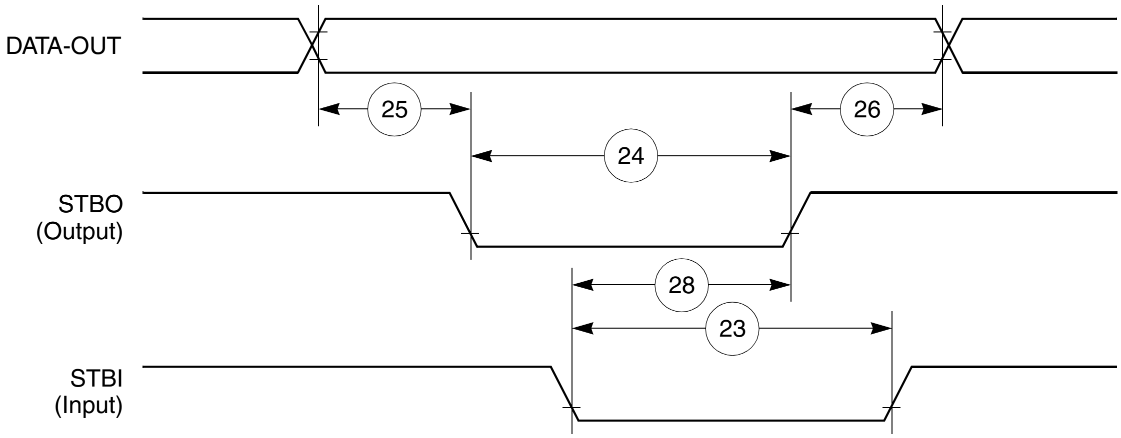


Figure 40. PIP Tx (Interlock Mode) Timing Diagram

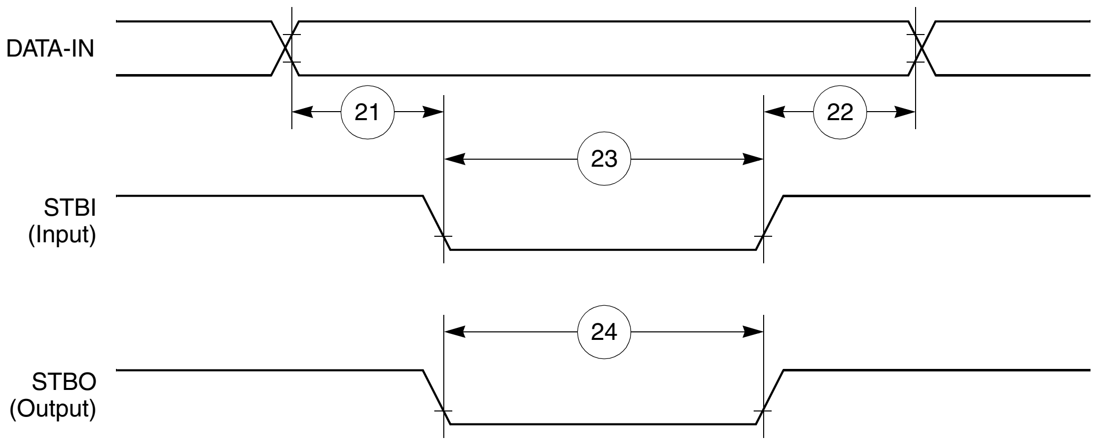


Figure 41. PIP Rx (Pulse Mode) Timing Diagram

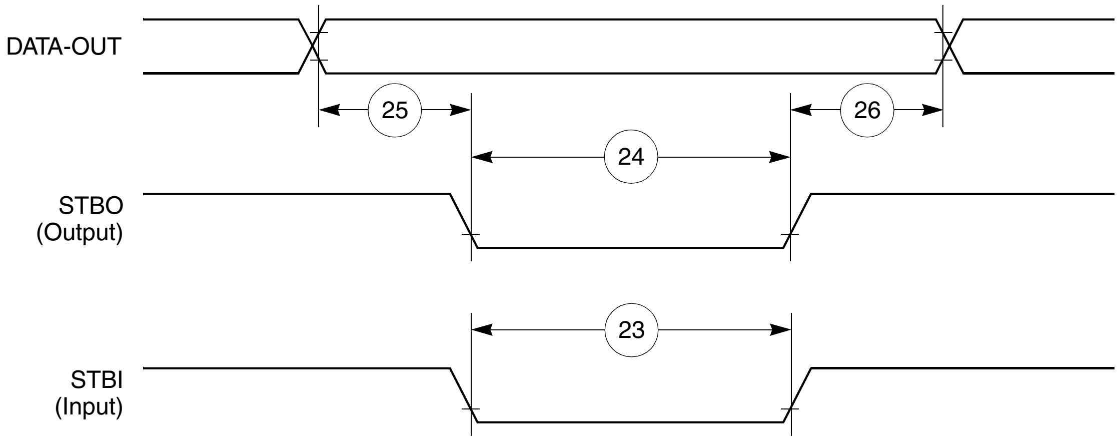


Figure 42. PIP TX (Pulse Mode) Timing Diagram

Table 16. IDMA Controller Timing (continued)

Num	Characteristic	All Frequencies		Unit
		Min	Max	
42	SDACK assertion delay from clock high	—	12	ns
43	SDACK negation delay from clock low	—	12	ns
44	SDACK negation delay from TA low	—	20	ns
45	SDACK negation delay from clock high	—	15	ns
46	TA assertion to rising edge of the clock setup time (applies to external TA)	7	—	ns

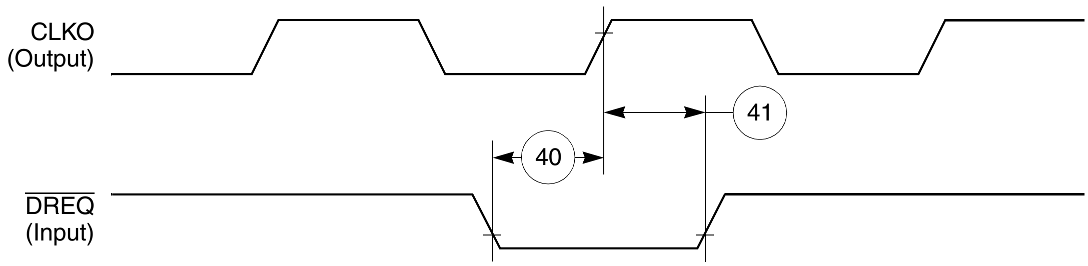


Figure 45. IDMA External Requests Timing Diagram

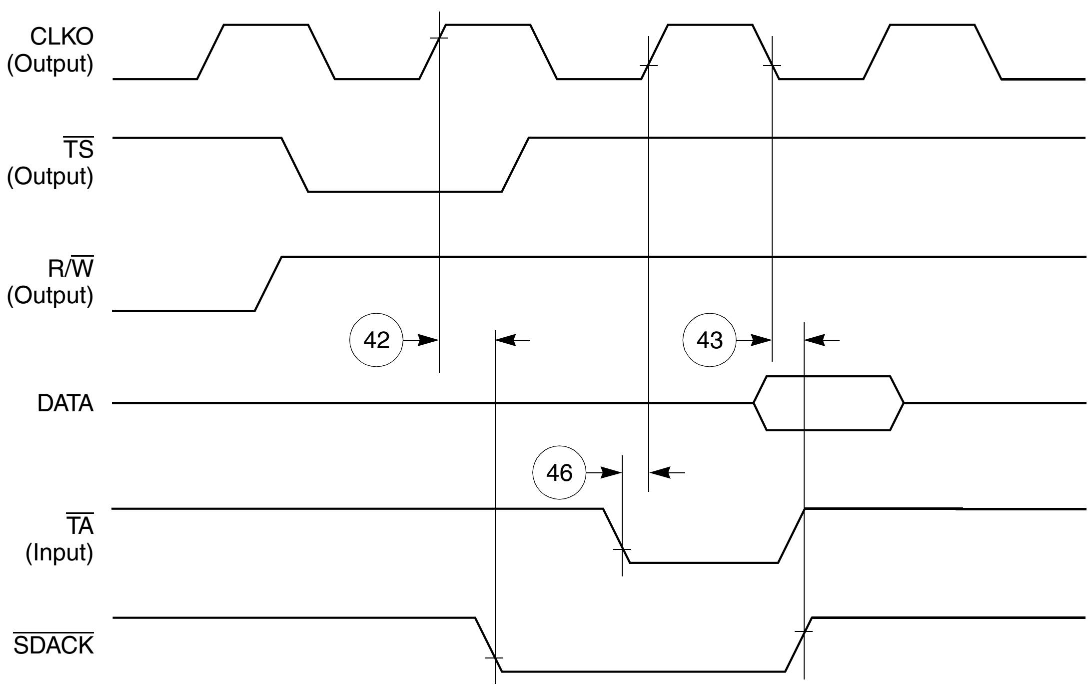


Figure 46. SDACK Timing Diagram—Peripheral Write, Externally-Generated TA

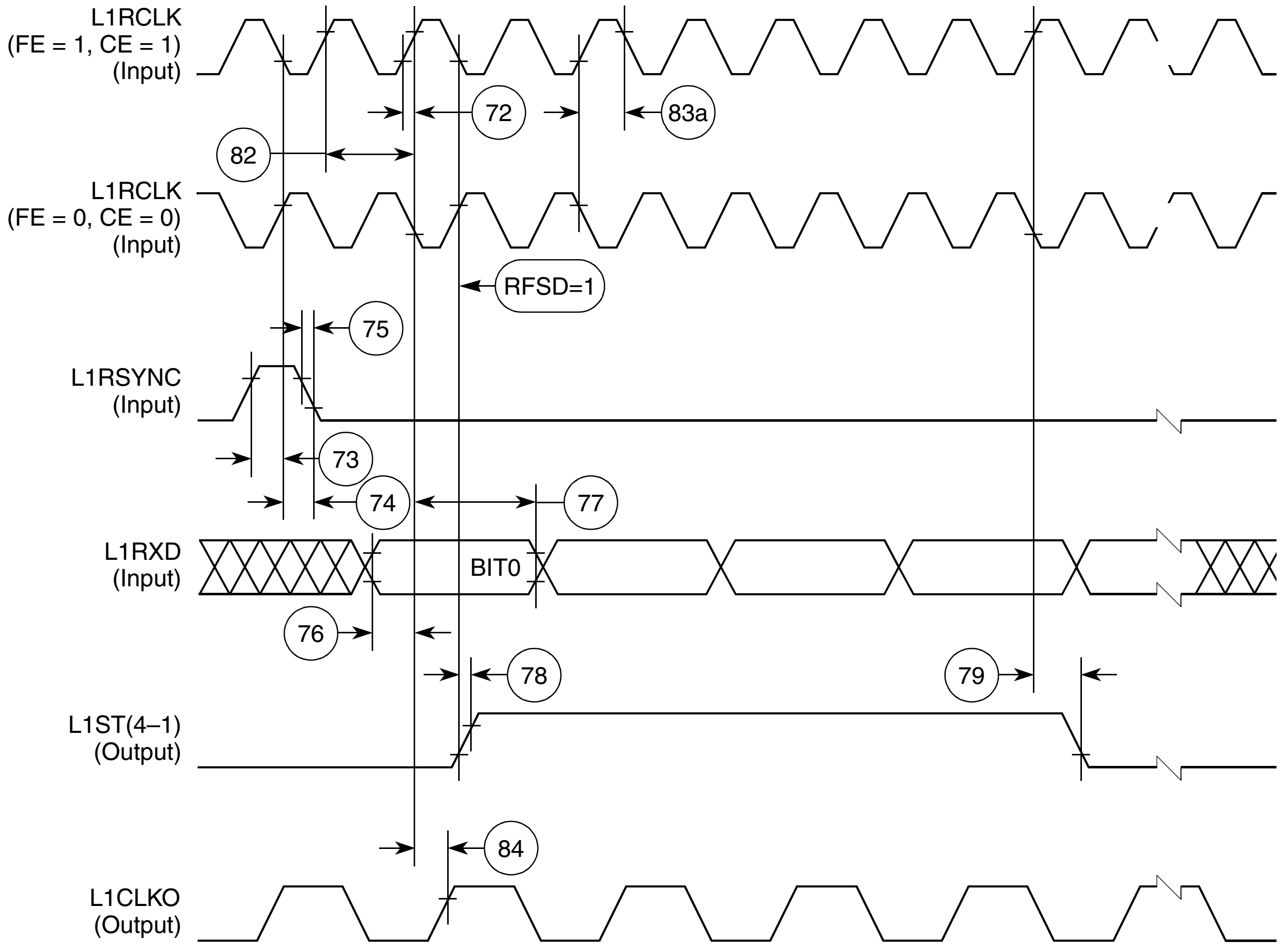
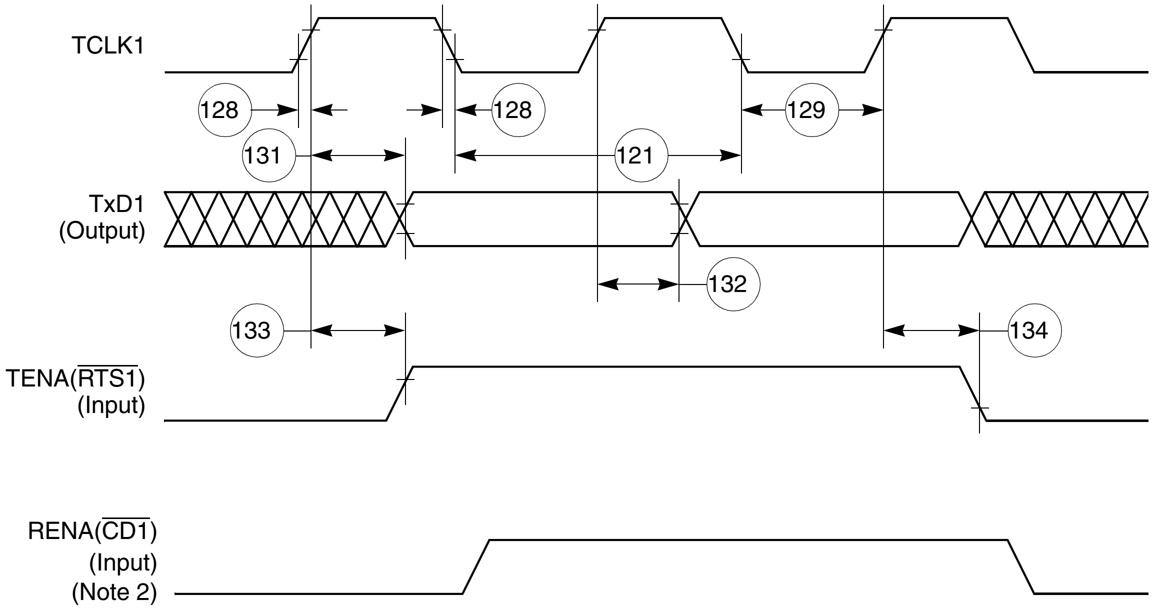


Figure 52. SI Receive Timing with Double-Speed Clocking (DSC = 1)



Notes:
1. Transmit clock invert (TCI) bit in GSMR is set.
2. If RENA is deasserted before TENA, or RENA is not asserted at all during transmit, then the CSL bit is set in the buffer descriptor at the end of the frame transmission.

Figure 61. Ethernet Transmit Timing Diagram

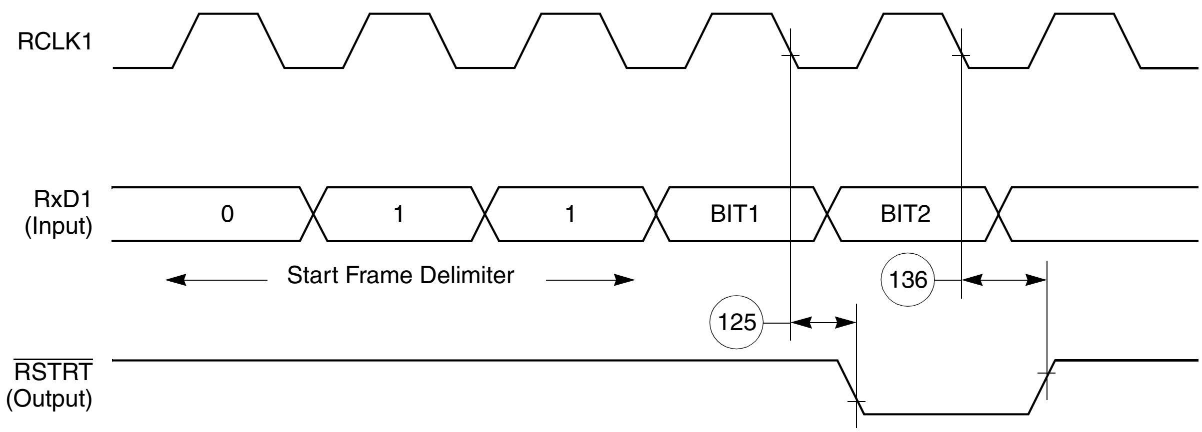


Figure 62. CAM Interface Receive Start Timing Diagram

Figure 63. CAM Interface REJECT Timing Diagram

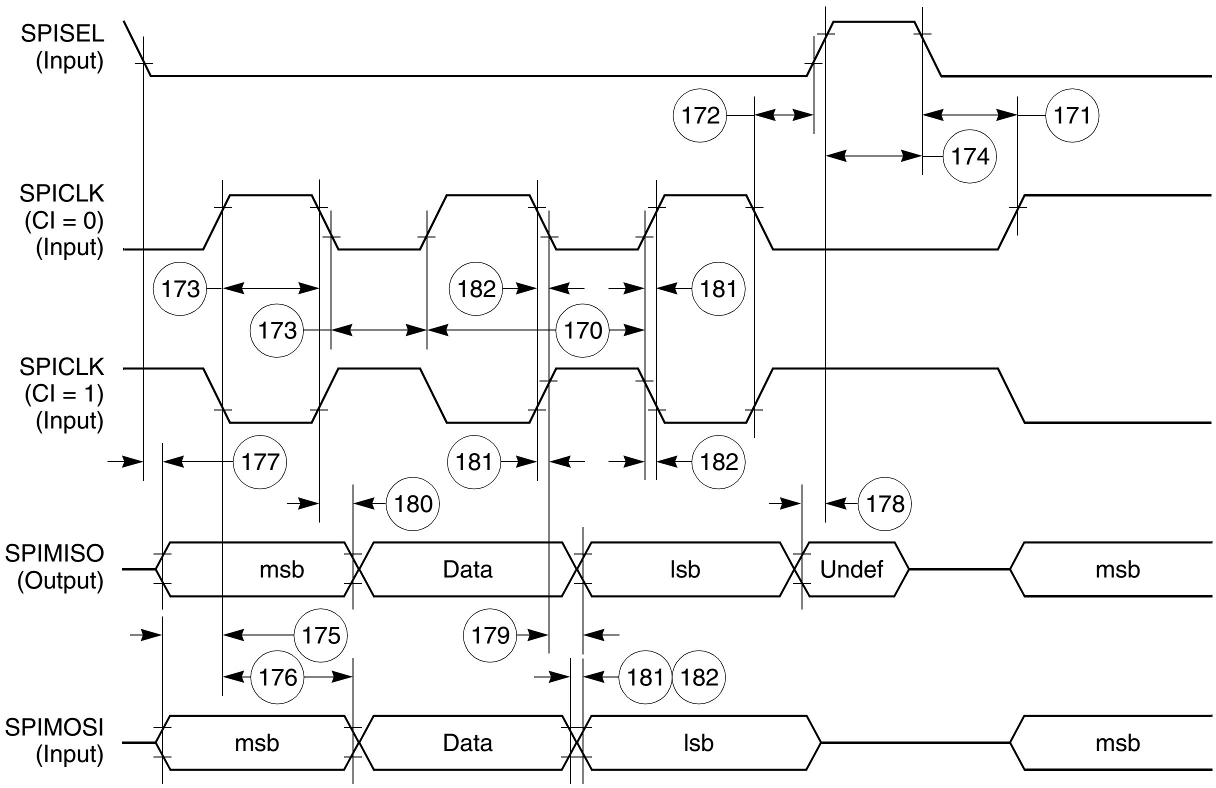


Figure 67. SPI Slave (CP = 0) Timing Diagram

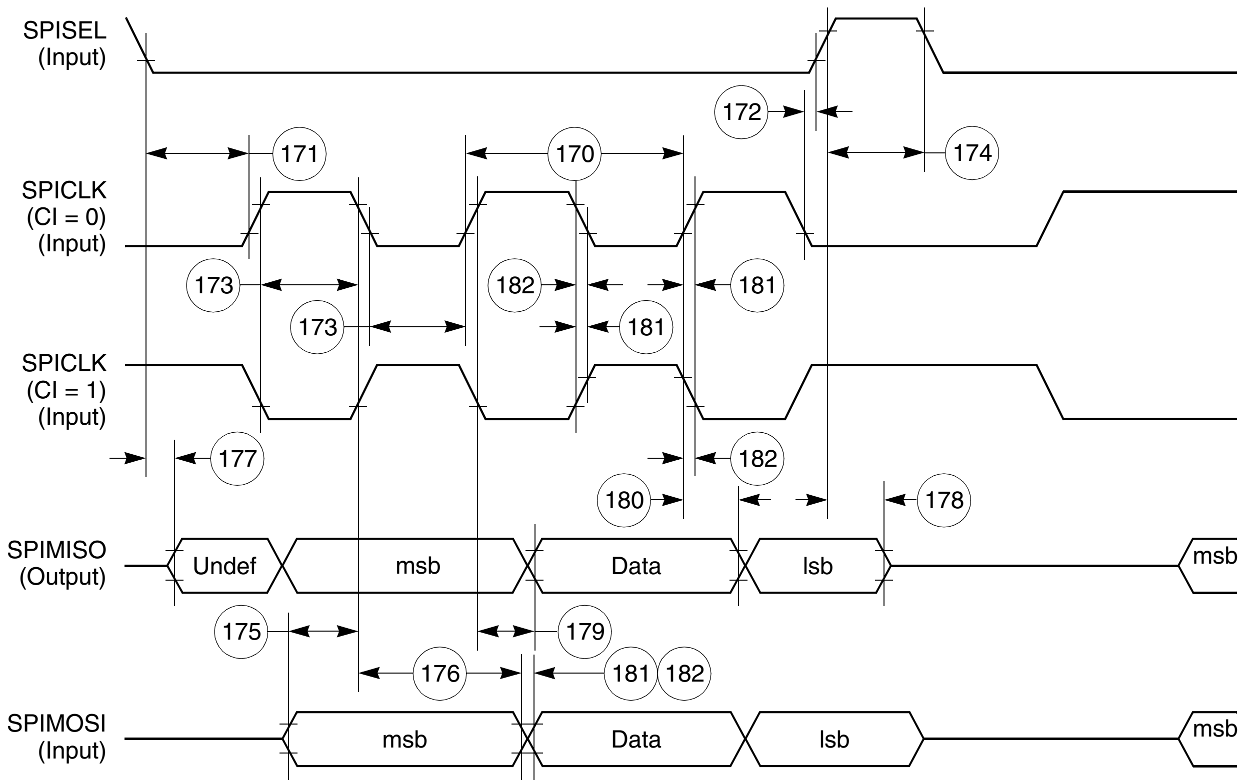


Figure 68. SPI Slave (CP = 1) Timing Diagram

Figure 70 shows signal timings during UTOPIA receive operations.

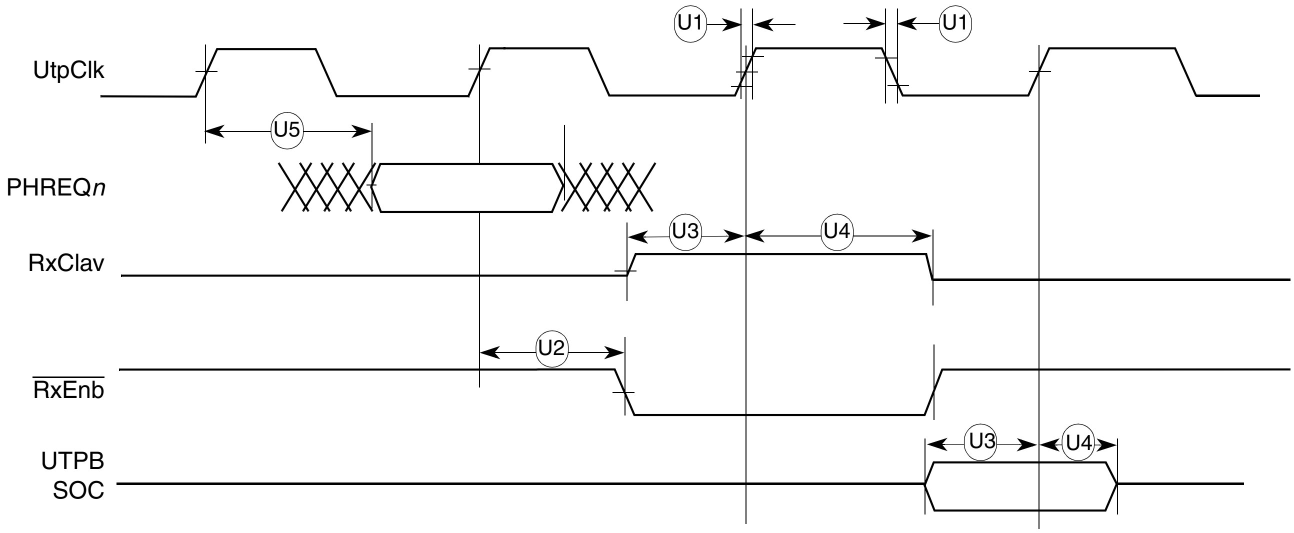


Figure 70. UTOPIA Receive Timing

Figure 71 shows signal timings during UTOPIA transmit operations.

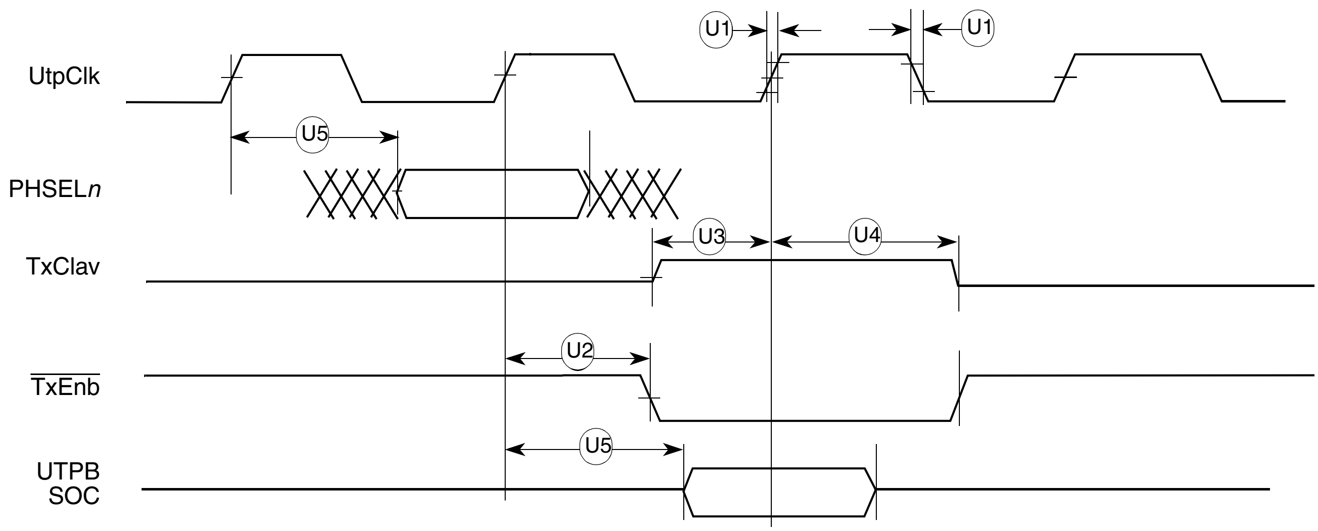


Figure 71. UTOPIA Transmit Timing

13.2 MII Transmit Signal Timing (MII_TXD[3:0], MII_TX_EN, MII_TX_ER, MII_TX_CLK)

The transmitter functions correctly up to a MII_TX_CLK maximum frequency of 25 MHz +1%. There is no minimum frequency requirement. In addition, the processor clock frequency must exceed the MII_TX_CLK frequency – 1%.

Table 30 provides information on the MII transmit signal timing.

Table 30. MII Transmit Signal Timing

Num	Characteristic	Min	Max	Unit
M5	MII_TX_CLK to MII_TXD[3:0], MII_TX_EN, MII_TX_ER invalid	5	—	ns
M6	MII_TX_CLK to MII_TXD[3:0], MII_TX_EN, MII_TX_ER valid	—	25	
M7	MII_TX_CLK pulse width high	35	65%	MII_TX_CLK period
M8	MII_TX_CLK pulse width low	35%	65%	MII_TX_CLK period

Figure 73 shows the MII transmit signal timing diagram.

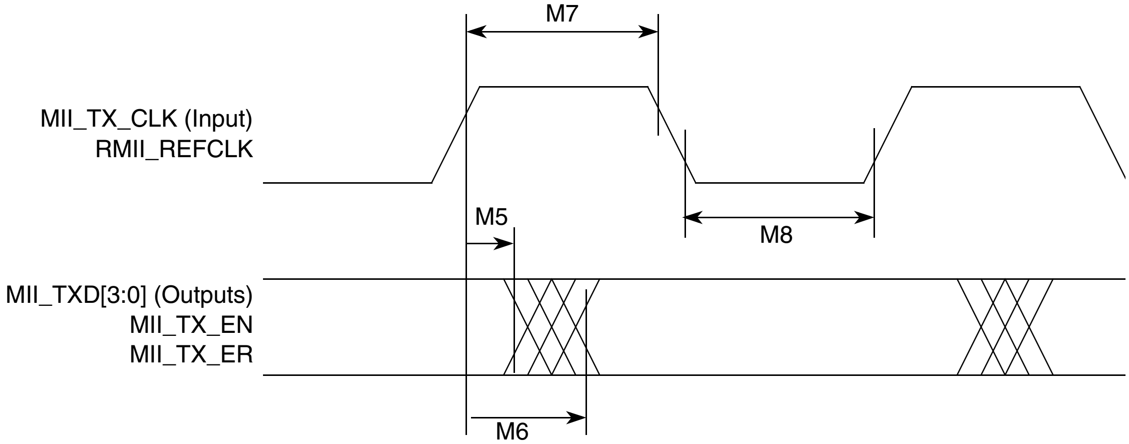


Figure 73. MII Transmit Signal Timing Diagram

14.2 Pin Assignments

Figure 76 shows the top view pinout of the PBGA package. For additional information, see the *MPC860 PowerQUICC User's Manual*, or the *MPC855T User's Manual*.

NOTE: This is the top view of the device.

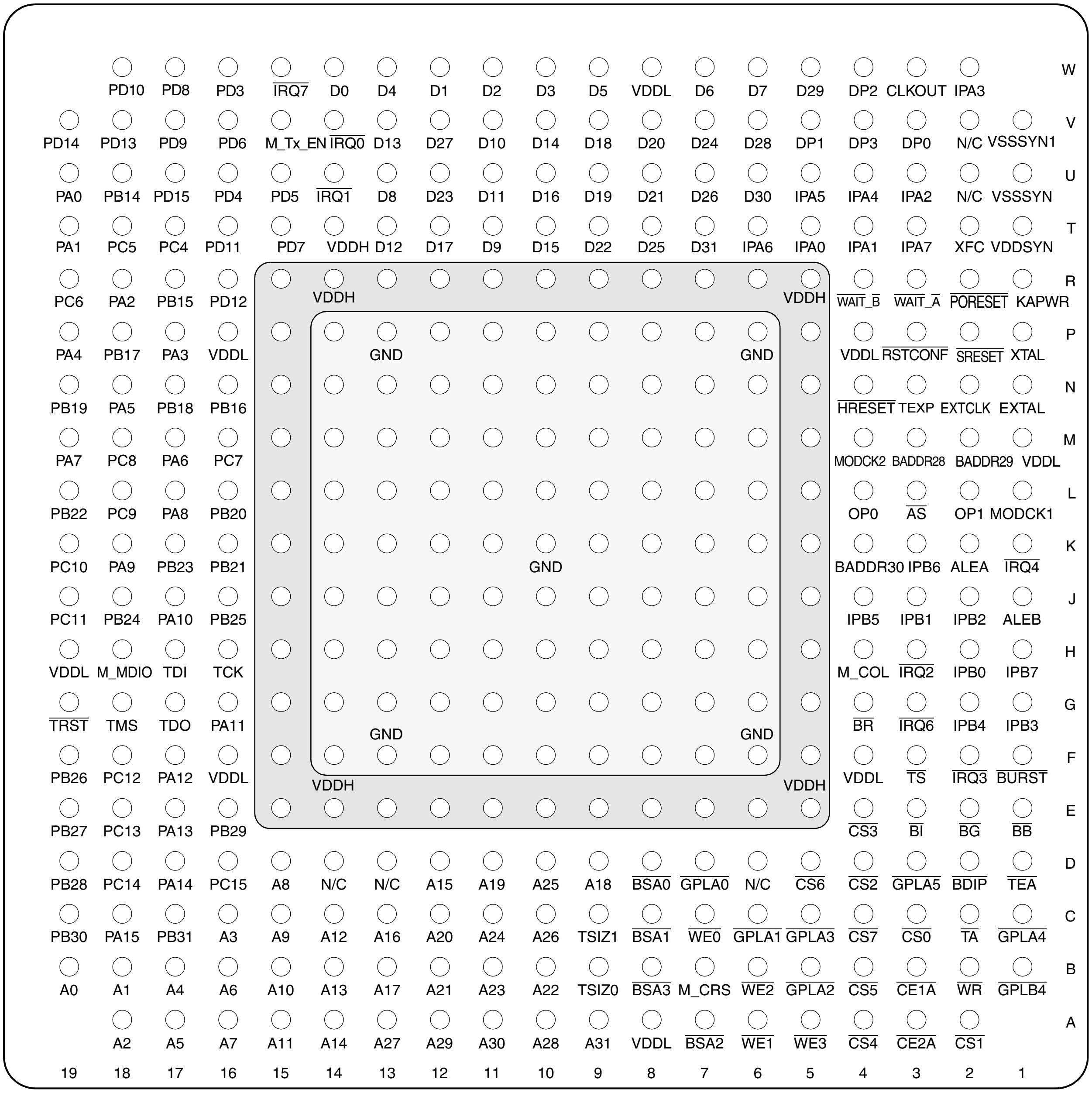
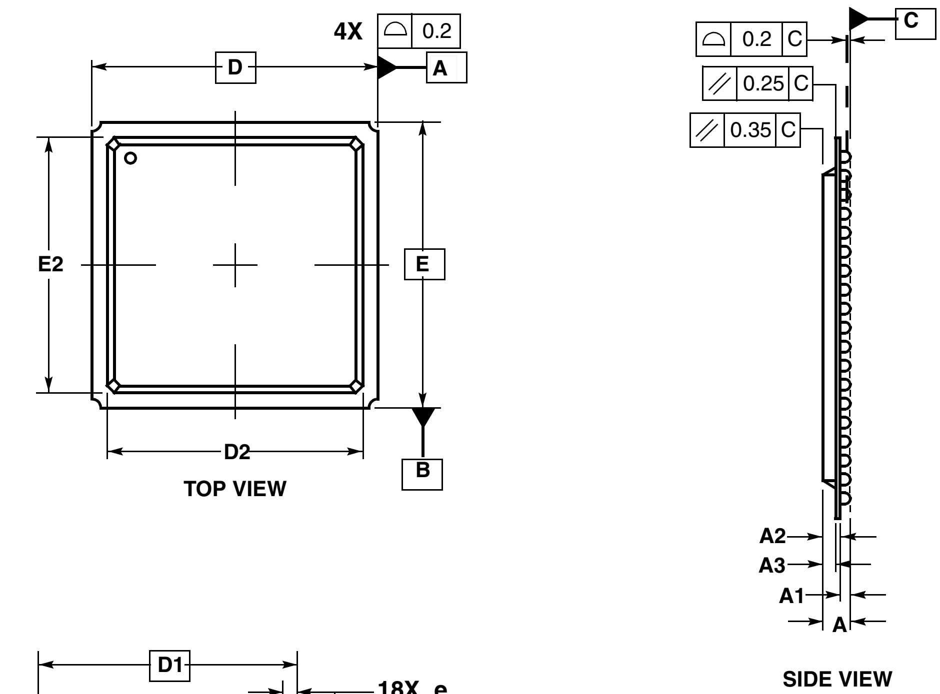
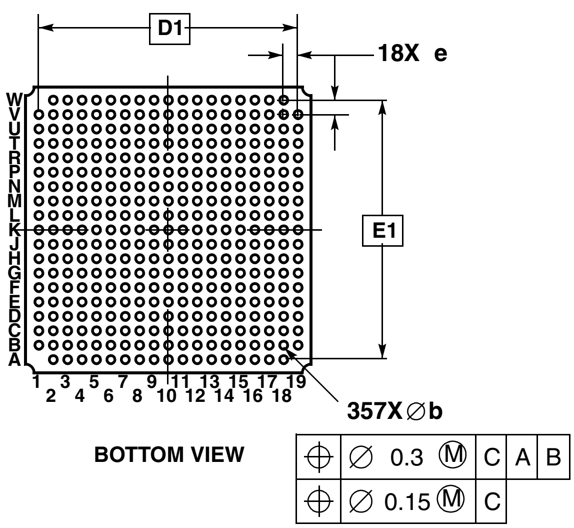


Figure 76. Pinout of the PBGA Package

14.3 Mechanical Dimensions of the PBGA Package

Figure 77 shows the mechanical dimensions of the ZP PBGA package.





	MILLIMETERS	
DIM	MIN	MAX
A	---	2.05
A1	0.50	0.70
A2	0.95	1.35
A3	0.70	0.90
b	0.60	0.90
D	25.00 BSC	
D1	22.86 BSC	
D2	22.40	22.60
e	1.27 BSC	
E	25.00 BSC	
E1	22.86 BSC	
E2	22.40	22.60

NOTE

1. Dimensions and tolerance per ASME Y14.5M, 1994.
2. Dimensions in millimeters.
3. Dimension b is the maximum solder ball diameter measured parallel to data C.

Figure 77. Mechanical Dimensions and Bottom Surface Nomenclature of the ZP PBGA Package

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